Micro-scale metallization on flexible polyimide substrate by NIL

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Technologies for flexible electronics have been developed to make electronic or microelectromechanical (MEMS) devices on inexpensive and flexible printed circuit board (FPCB). In order to fabricate the interconnect lines between device elements or layers in flexible electronic devices, metallization on the flexible substrate is essential. In this case, the width and conductivity of metallization process with the scale of a few micrometers on the flexible substrate is required. In conventional FPCB fabrication process, photolithography have been used. In this work, metalliztion on the flexible substrate is fabricated with NIL(Nano imprinted lithography). Polystylene was spin-coated and patterned by NIL. FPCB fabricated by NIL have many merits that are a low-cost, large-area, high-resolution.